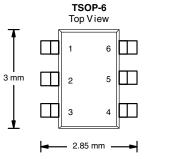


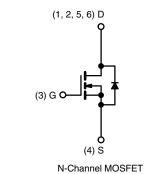
**Vishay Siliconix** 

# Automotive N-Channel 30 V (D-S) 175 °C MOSFET

PRODUCT SUMMARY				
V <sub>DS</sub> (V)	30			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 V$	0.035			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 4.5 V$	0.052			
I <sub>D</sub> (A)	7.8			
Configuration	Single			



Marking Code: 8Lxxx



#### **FEATURES**

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET<sup>®</sup> Power MOSFET
- Compliant to RoHS Directive 2002/95/EC
- AEC-Q101 Qualified<sup>c</sup>



HALOGEN FREE

ORDERING INFORMATION	
Package	TSOP-6
Lead (Pb)-free and Halogen-free	SQ3456BEV-T1-GE3

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25 °C, unless otherwise noted)					
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage		V <sub>DS</sub>	30	N/	
Gate-Source Voltage		V <sub>GS</sub>	± 20	V	
Continuous Drain Current	T <sub>C</sub> = 25 °C	- I <sub>D</sub>	7.8		
	T <sub>C</sub> = 125 °C		4.5		
Continuous Source Current (Diode Conduction)		I <sub>S</sub>	5	А	
Pulsed Drain Current <sup>a</sup>		I <sub>DM</sub>	31		
Single Pulse Avalanche Current	1 0.1 mll	I <sub>AS</sub>	10		
Single Pulse Avalanche Energy	L = 0.1 mH	E <sub>AS</sub>	5	mJ	
Maximum Power Dissipation <sup>a</sup>	T <sub>C</sub> = 25 °C	- P <sub>D</sub>	4	W	
	T <sub>C</sub> = 125 °C		1.3	٧V	
Operating Junction and Storage Temperature F	lange	T <sub>J</sub> , T <sub>stg</sub>	- 55 to + 175	°C	

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	LIMIT	UNIT	
Junction-to-Ambient	PCB Mount <sup>b</sup>	R <sub>thJA</sub>	110	°C/W	
Junction-to-Foot (Drain)	to-Foot (Drain)		38	0/₩	

#### Notes

a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.

b. When mounted on 1" square PCB (FR-4 material).

c. Parametric verification ongoing.

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PARAMETER	SYMBOL	TES	TEST CONDITIONS		TYP.	MAX.	UNIT
Static				<u> </u>	1	<b>I</b>	
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 V, I_D = 250 \mu A$		30	-	-	v
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$		2.0	2.5	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 20 V$		-	-	± 100	nA
Zero Gate Voltage Drain Current		$V_{GS} = 0 V$	V <sub>DS</sub> = 30 V	-	-	1	μA
	I <sub>DSS</sub>	$V_{GS} = 0 V$	$V_{DS} = 30 \text{ V}, \text{ T}_{J} = 125 ^{\circ}\text{C}$	-	-	50	
		$V_{GS} = 0 V$	V <sub>DS</sub> = 30 V, T <sub>J</sub> = 175 °C	-	-	150	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>GS</sub> = 10 V	$V_{DS} \ge 5 V$	10	-	-	Α
Drain-Source On-State Resistance <sup>a</sup>		V <sub>GS</sub> = 10 V	I <sub>D</sub> = 6 A	-	0.028	0.035	Ω
	<b>D</b>	V <sub>GS</sub> = 4.5 V	I <sub>D</sub> = 4.9 A	-	0.036	0.052	
	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 6 A, T <sub>J</sub> = 125 °C	-	-	0.054	
		V <sub>GS</sub> = 10 V	I <sub>D</sub> = 6 A, T <sub>J</sub> = 175 °C	-	-	0.064	
Forward Transconductanceb	9 <sub>fs</sub>	V <sub>DS</sub>	= 15 V, I <sub>D</sub> = 5 A	-	21	-	S
Dynamic <sup>b</sup>	-						
Input Capacitance	C <sub>iss</sub>		V <sub>GS</sub> = 0 V V <sub>DS</sub> = 15 V, f = 1 MHz	-	295	370	pF
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 V$		-	67	85	
Reverse Transfer Capacitance	C <sub>rss</sub>			-	25	35	
Total Gate Charge <sup>c</sup>	Qg	V <sub>GS</sub> = 10 V	$V_{GS} = 10 \text{ V}$ $V_{DS} = 15 \text{ V}, I_D = 6 \text{ A}$	-	6	10	nC
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>			-	1.2	-	
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			-	1	-	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>	V <sub>DD</sub> = 15 V, R <sub>L</sub> = 2.5 Ω I <sub>D</sub> ≅ 6 A, V <sub>GEN</sub> = 10 V, R <sub>g</sub> = 1 Ω		-	6	9	
Rise Time <sup>c</sup>	t <sub>r</sub>			-	12	18	ns
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>			-	13	20	
Fall Time <sup>c</sup>	t <sub>f</sub>			-	8	12	
Source-Drain Diode Ratings and Chara	acteristics <sup>b</sup>	•		•			
Pulsed Current <sup>a</sup>	I <sub>SM</sub>			-	-	31	А
Forward Voltage	V <sub>SD</sub>	$I_{F} = 3 A, V_{GS} = 0 V$		-	0.8	1.1	V

Notes

a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.

b. Guaranteed by design, not subject to production testing.

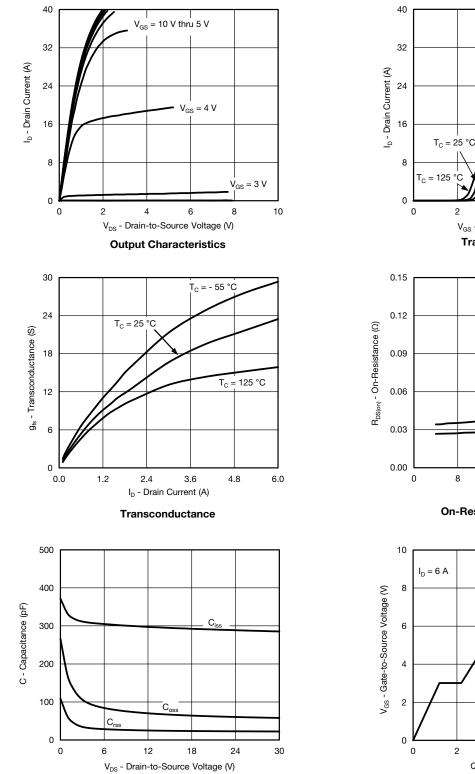
c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

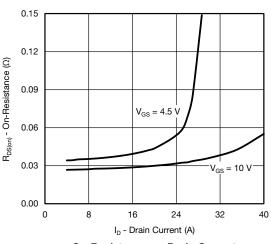
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#### **TYPICAL CHARACTERISTICS** ( $T_A = 25$ °C, unless otherwise noted)



- 55 °C

6

8

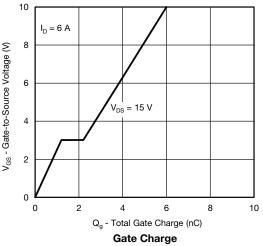
10

T<sub>C</sub>

V<sub>GS</sub> - Gate-to-Source Voltage (V) **Transfer Characteristics** 

Δ

**On-Resistance vs. Drain Current** 



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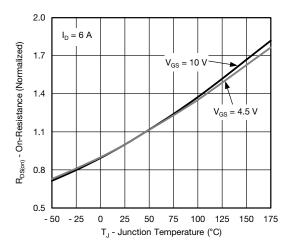
Capacitance

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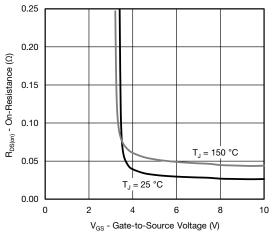
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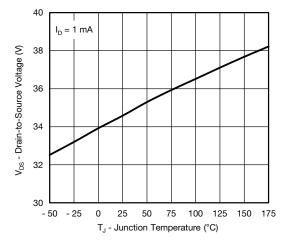
#### **TYPICAL CHARACTERISTICS** ( $T_A = 25 \text{ °C}$ , unless otherwise noted)



**On-Resistance vs. Junction Temperature** 



On-Resistance vs. Gate-to-Source Voltage

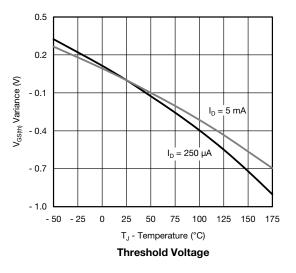


Drain Source Breakdown vs. Junction Temperature

10 ĒT<sub>J.</sub>= 150 °C I<sub>s</sub> - Source Current (A) 1 0.1 = 25 °C Т, 0.01 0.001 0.2 0.0 0.4 0.6 0.8 1.0 1.2 V<sub>SD</sub> - Source-to-Drain Voltage (V)

100

Source-Drain Diode Forward Voltage

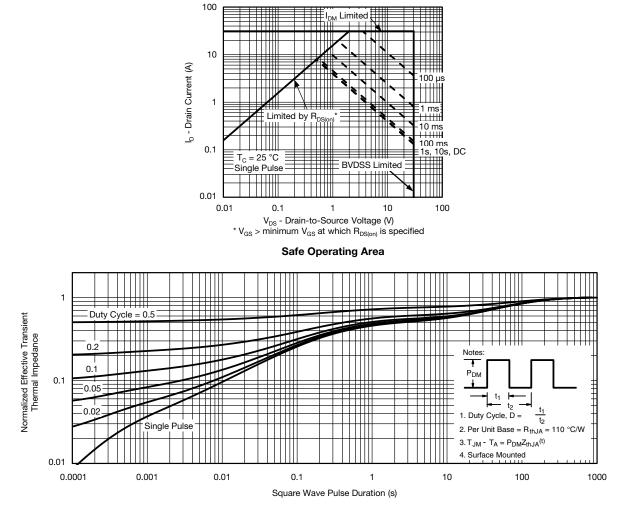


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#### **THERMAL RATINGS** ( $T_A = 25 \text{ °C}$ , unless otherwise noted)

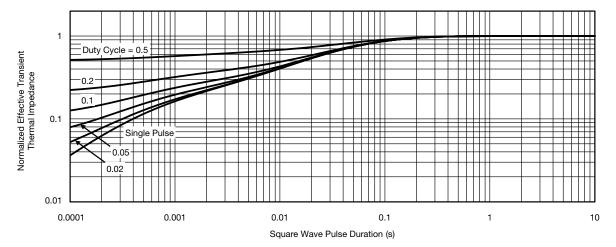


Normalized Thermal Transient Impedance, Junction-to-Ambient

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**THERMAL RATINGS** ( $T_A = 25 \text{ °C}$ , unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Foot

### Note

The characteristics shown in the two graphs

- Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)

- Normalized Transient Thermal Impedance Junction-to-Foot (25 °C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see <a href="https://www.vishay.com/ppg267934">www.vishay.com/ppg267934</a>.

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